

Electronic Patent Application Fee Transmittal

Application Number:	10657505			
Filing Date:	08-Sep-2003			
Title of Invention:	METHOD OF MANUFACTURING A CONTACT INTERCONNECTION LAYER CONTAINING A METAL AND NITROGEN BY ATOMIC LAYER DEPOSITION FOR DEEP SUB-MICRON SEMICONDUCTOR TECHNOLOGY			
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Attorney Docket Number:	TS01-1247			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
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